

HOSTAFORM® S 9364 LPB

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Hostaform® acetal copolymer grade S 9364LPB is a highly impact modified grade for low permeation. Hostaform® S 9364LPB provides a significant improvement in impact strength and flexibility over standard impact modified grades. Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM-I	ISO 1043
Part Marking Code	>POM-I<	ISO 11469

Rheological properties

Melt volume-flow rate	0.6 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile modulus	1650 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	43 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	16 %	ISO 527-1/-2
Flexural modulus	1550 MPa	ISO 178
Charpy impact strength, 23°C	N kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	N kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	21 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	11 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.42 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	75 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110 E-6/K	ISO 11359-1/-2

Physical/Other properties

Water absorption, 2mm	0.8 %	Sim. to ISO 62
Density	1370 kg/m ³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	195 °C
Min. melt temperature	180 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	65 °C
Min. mould temperature	60 °C

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Max. mould temperature 70 °C
Hold pressure range 60 - 120 MPa

Characteristics

Processing	Injection Moulding, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified

Additional information

Processing Notes

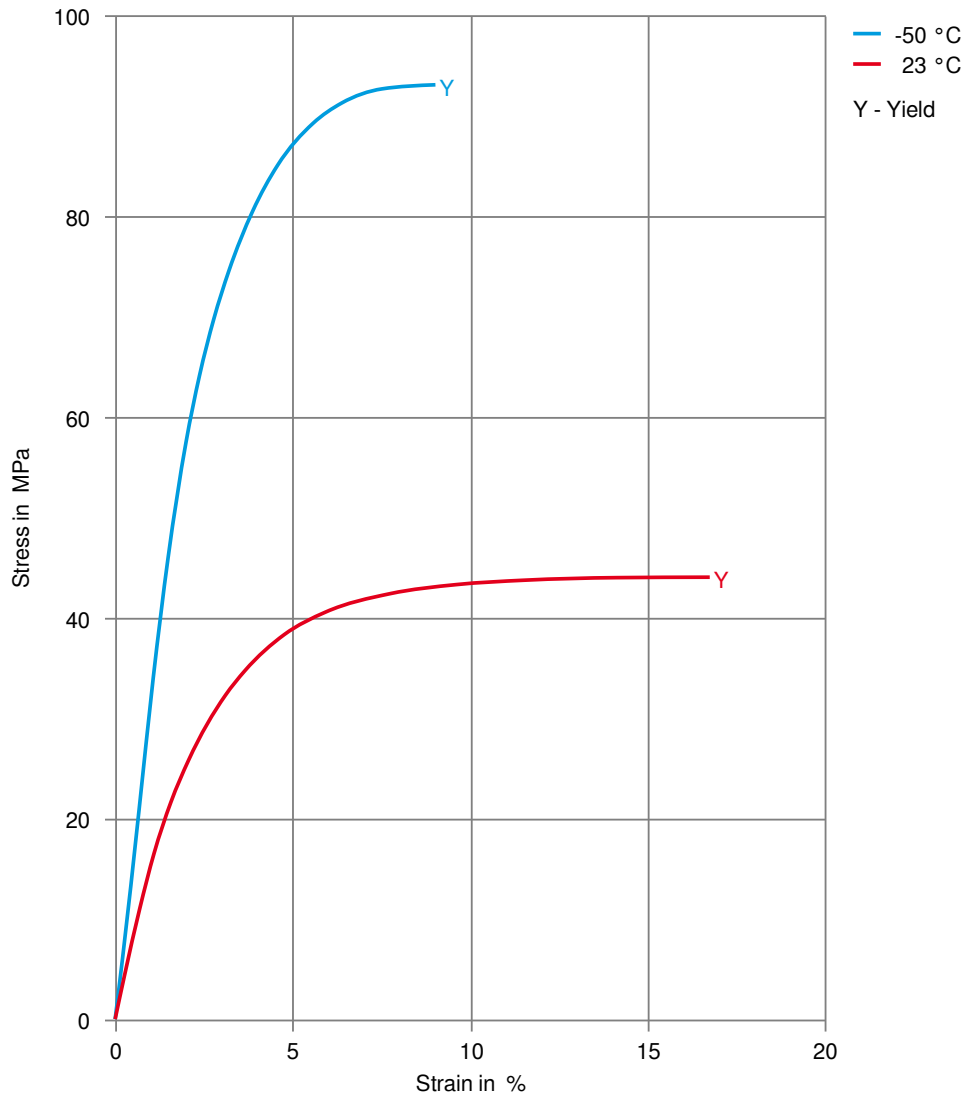
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying to prevent splay and odor problems.

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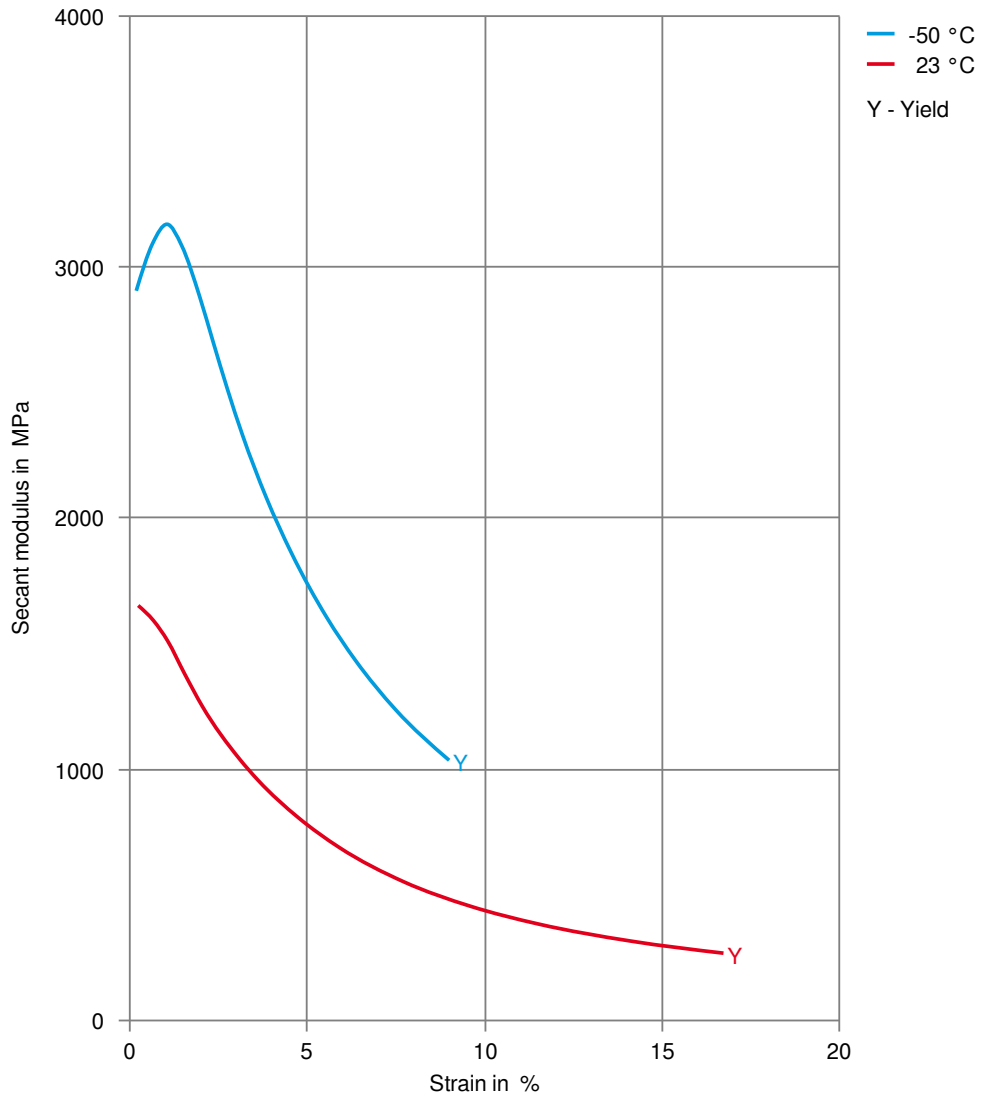
Stress-strain



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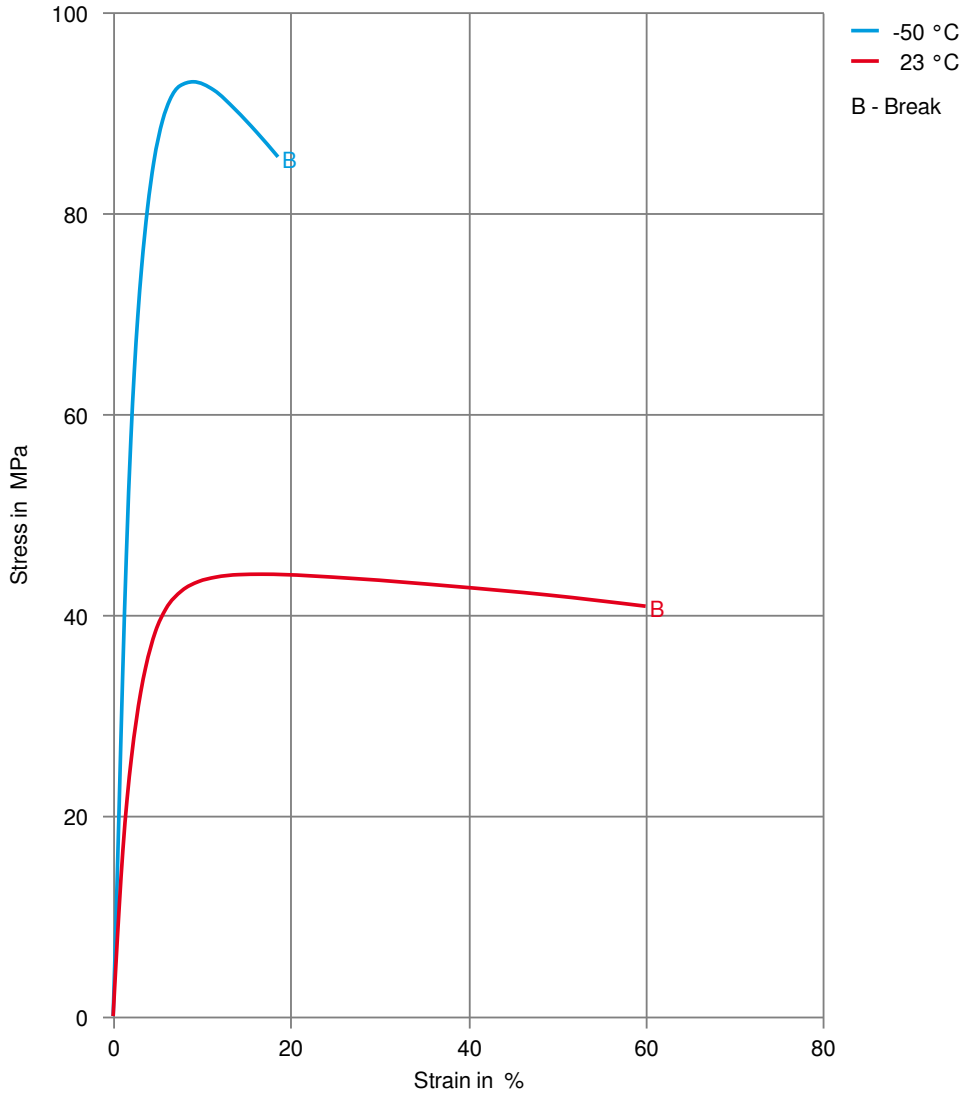
Secant modulus-strain



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Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min

